TEXAS INSTRUMENTS

SN74LVC1G14

SCES218Y – APRIL 1999 – REVISED NOVEMBER 2018

SN74LVC1G14 Single Schmitt-Trigger Inverter

1 Features

- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4.6 ns at 3.3 V
- Low Power Consumption, 10-µA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation

2 Applications

- AV Receiver
- Audio Dock: Portable
- Blu-ray Player and Home Theater
- Embedded PC
- MP3 Player/Recorder (Portable Audio)
- Personal Digital Assistant (PDA)
- Power: Telecom/Server AC/DC Supply: Single Controller: Analog and Digital
- Solid State Drive (SSD): Client and Enterprise
- TV: LCD/Digital and High-Definition (HDTV)
- Tablet: Enterprise
- Video Analytics: Server
- Wireless Headset, Keyboard, and Mouse

3 Description

This single Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G14 device contains one inverter and performs the Boolean function $Y = \overline{A}$. The device functions as an independent inverter with Schmitt-trigger inputs, so the device has different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals to provide hysteresis (ΔV_T) which makes the device tolerant to slow or noisy input signals.
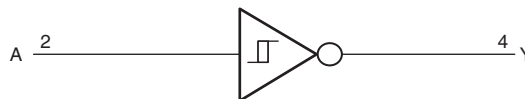
NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs when the device is powered down. This inhibits current backflow into the device which prevents damage to the device.

Device Information

ORDER NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LVC1G14DBV	SOT-23 (5)	2.90 mm × 1.60 mm
SN74LVC1G14DCK	SC70 (5)	2.00 mm × 1.25 mm
SN74LVC1G14DRL	SOT-5X3 (5)	1.60 mm × 1.20 mm
SN74LVC1G14DRY	SON (6)	1.45 mm × 1.00 mm
SN74LVC1G14DSF	SON (6)	1.00 mm × 1.00 mm
SN74LVC1G14YZP	DSBGA (5)	1.39 mm × 0.89 mm
SN74LVC1G14YZV	DSBGA (4)	0.89 mm × 0.89 mm
SN74LVC1G14DPW	X2SON (5)	0.80 mm x 0.80 mm

Logic Diagram (Positive Logic)
(DBV, DCK, DRL, DRY, DPW, and YZP Package)

A 2 ———————▷〇——————— 4 Y

Logic Diagram (Positive Logic)
(YZV Package)

A 1 ———————▷〇——————— 3 Y

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision X (August 2017) to Revision Y   **Page**

Changes from Revision W (March 2014) to Revision X   **Page**

Changes from Revision V (Novmber 2012) to Revision W   **Page**

5 Pin Configuration and Functions

DBV Package
5-Pin SOT-23
Top View

DCK Package
5-Pin SC70
Top View

DRL Package
5-Pin SOT-5X3
Top View

DRY Package
6-Pin SON
Top View

DPW Package
5-Pin X2SON
Top View

DSF Package
6-Pin SON
Top View
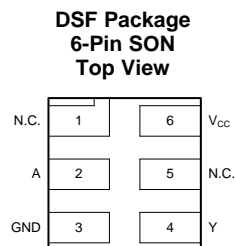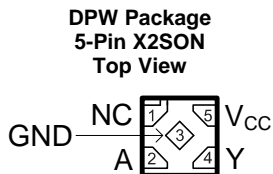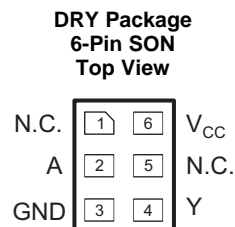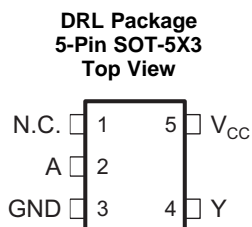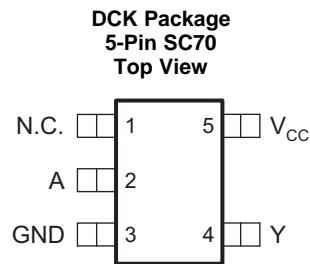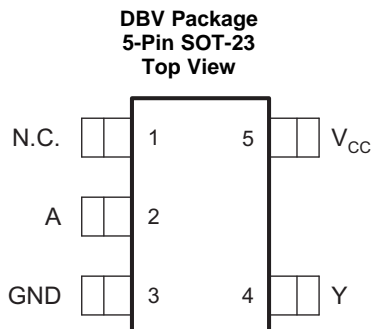
See mechanical drawings for dimensions.

N.C. – No internal connection

YZP Package
5-Pin DSBGA
Bottom View

DNU – Do not use

YZV Package
4-Pin DSBGA
Bottom View

Product Folder Links: SN74LVC1G14
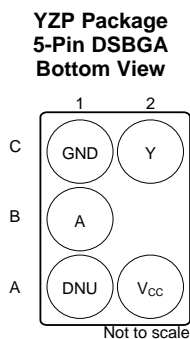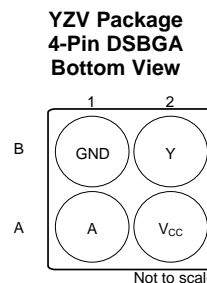
Pin Functions

PIN					I/O	DESCRIPTION
NAME	DBV, DCK, DRL, DPW	DRY, DSF	YZP	YZV		
A	2	2	B1	A1	I	Signal Input
GND	3	3	C1	B1	—	Ground
N.C.	1	1, 5	—	—	—	No internal connection[1]
DNU	—	—	A1	—	—	Do not use[2]
V_{CC}	5	6	A2	A2	—	Positive Supply
Y	4	4	C2	B2	O	Signal Output

(1) Pins labeled N.C. can be connected to any signal or voltage source, including ground. They should always be soldered to the board.
(2) Pins labeled DNU should not be connected to any signal or voltage source, including ground. They should always be soldered to the board.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)[1]

			MIN	MAX	UNIT
V_{CC}	Supply voltage		−0.5	6.5	V
V_I	Input voltage [2]		−0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state[2]		−0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state[2] [3]		−0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	$V_I < 0$		−50	mA
I_{OK}	Output clamp current	$V_O < 0$		−50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T_j	Maximum junction temperature			150	°C
T_{stg}	Storage temperature		−65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The value of V_{CC} is provided in the recommended operating conditions table.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001[1]	2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101[2]	1000	
		Machine Model (A115-A)	200	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)[1]

			MIN	MAX	UNIT
V_{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V_I	Input voltage		0	5.5	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65 V		−4	mA
		V_{CC} = 2.3 V		−8	
		V_{CC} = 3 V		−16	
				−24	
		V_{CC} = 4.5 V		−32	
I_{OL}	Low-level output current	V_{CC} = 1.65 V		4	mA
		V_{CC} = 2.3 V		8	
		V_{CC} = 3 V		16	
				24	
		V_{CC} = 4.5 V		32	
T_A	Operating free-air temperature	YZP, YZV, and DPW packages	−40	85	°C
		All other packages	−40	125	

(1) All unused inputs of the device must be held at V_{CC} or GND to assure proper device operation. See *Implications of Slow or Floating CMOS Inputs*.

6.4 Thermal Information

	THERMAL METRIC[1]	SN74LVC1G14							UNIT
		DBV (SOT-23)	DCK (SC70)	DRL (SOT-5X3)	DRY (SON)	DPW (X2SON)	YZV (DSBGA)	YZP (DSBGA)	
		5 PINS	5 PINS	5 PINS	5 PINS	5 PINS	4 PINS	5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	247.2	276.1	296.2	369.6	522.9	168.2	146.2	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	154.5	178.9	137.3	257.6	250.5	2.1	1.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	86.8	70.9	145.3	230.8	384.0	55.9	39.8	°C/W
ψ_{JT}	Junction-to-top characterization parameter	58.0	47.0	14.7	77.2	46.5	1.1	0.7	°C/W
ψ_{JB}	Junction-to-board characterization parameter	86.4	69.3	145.9	231.0	382.8	56.3	39.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	174.1	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	−40°C to 85°C			−40°C to 125°C[1]			UNIT
				MIN	TYP[2]	MAX	MIN	TYP	MAX	
V_{T+} Positive-going input threshold voltage			1.65 V	0.79		1.16	.79		1.16	V
			2.3 V	1.11		1.56	1.11		1.56	
			3 V	1.5		1.87	1.5		1.87	
			4.5 V	2.16		2.74	2.16		2.74	
			5.5 V	2.61		3.33	2.61		3.33	
V_{T-} Negative-going input threshold voltage		DBV, DCK, DRL, DRY, DSF, YZV and YZP packages	1.65 V	0.39		0.62	.39		.64	V
			2.3 V	0.58		0.87	.58		.89	
			3 V	0.84		1.14	.84		1.16	
			4.5 V	1.41		1.79	1.41		1.79	
			5.5 V	1.87		2.29	1.87		2.29	
V_{T-} Negative-going input threshold voltage		DPW package	1.65 V	0.44		0.67				V
			2.3 V	0.63		0.92				
			3 V	0.89		1.19				
			4.5 V	1.46		1.84				
			5.5 V	1.92		2.34				
ΔV_T Hysteresis (V_{T+} − V_{T-})			1.65 V	0.37		0.62	0.37		0.62	V
			2.3 V	0.48		0.77	0.48		0.77	
			3 V	0.56		0.87	0.56		0.87	
			4.5 V	0.71		1.04	0.71		1.04	
			5.5 V	0.71		1.11	0.71		1.11	
V_{OH}		$I_{OL} = -100$ μA	1.65 V to 4.5 V	$V_{CC} - 0.1$			$V_{CC} - 0.1$			V
		$I_{OL} = -4$ mA	1.65 V	1.2			1.2			
		$I_{OL} = -8$ mA	2.3 V	1.9			1.9			
		$I_{OL} = -16$ mA	3 V	2.4			2.4			
		$I_{OL} = -24$ mA		2.3			2.3			
		$I_{OL} = -32$ mA	4.5 V	3.8			3.8			
V_{OL}		$I_{OL} = 100$ μA	1.65 V to 4.5 V			0.1			0.1	V
		$I_{OL} = 4$ mA	1.65 V			0.45			0.45	
		$I_{OL} = 8$ mA	2.3 V			0.3			0.3	
		$I_{OL} = 16$ mA	3 V			0.4			0.4	
		$I_{OL} = 24$ mA				0.55			0.55	
		$I_{OL} = 32$ mA	4.5 V			0.55			0.7	
I_I	A input	$V_I = 5.5$ V or GND	0 to 5.5 V			±5			±5	μA
I_{off}		V_I or $V_O = 5.5$ V	0			±10			±10	μA
I_{CC}		$V_I = 5.5$ V or GND, $I_O = 0$	1.65 V to 5.5 V			10			10	μA
ΔI_{CC}		One input at $V_{CC} - 0.6$ V, Other inputs at V_{CC} or GND	3 V to 5.5 V			500			500	μA
C_i		$V_I = V_{CC}$ or GND	3.3 V		4.5			4.5		pF

(1) These specifications do not apply to DPW, YZV and YZP packages. DPW, YZV and YZP have a recommended operating free-air temperature range of −40°C to 85°C.
(2) All typical values are at $V_{CC} = 3.3$ V, $T_A = 25$°C.

Product Folder Links: *SN74LVC1G14*

6.6 Switching Characteristics: –40°C to 85°C

over recommended operating free-air temperature range, (–40°C to 85°C unless otherwise noted) (see)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	C_L = 15 pF		C_L = 30 pF or 50 pF		UNIT
				MIN	MAX	MIN	MAX	
t_{pd}	A	Y	1.8 V ± 0.15 V	2.8	9.9	3.8	11	ns
			2.5 V ± 0.2 V	1.6	5.5	2	6.5	
			3.3 V ± 0.3 V	1.5	4.6	1.8	5.5	
			5 V ± 0.5 V	0.9	4.4	1.2	5	

6.7 Switching Characteristics: –40°C to 125°C

over operating free-air temperature range, (–40°C to 125°C unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	C_L = 30 pF or 50 pF		UNIT
				MIN	MAX	
t_{pd}	A	Y	1.8 V ± 0.15 V	3.8	13	ns
			2.5 V ± 0.2 V	2	8	
			3.3 V ± 0.3 V	1.8	6.5	
			5 V ± 0.5 V	1.2	6	

6.8 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10 MHz	1.8 V	20	pF
			2.5 V	21	
			3.3 V	22	
			5 V	25	

6.9 Typical Characteristics

T_A = 25°C

Figure 1. Typical V_{OH} vs I_{OH} - 25°C

Figure 2. Typical V_{OL} vs I_{OL} - 25°C

Product Folder Links: SN74LVC1G14
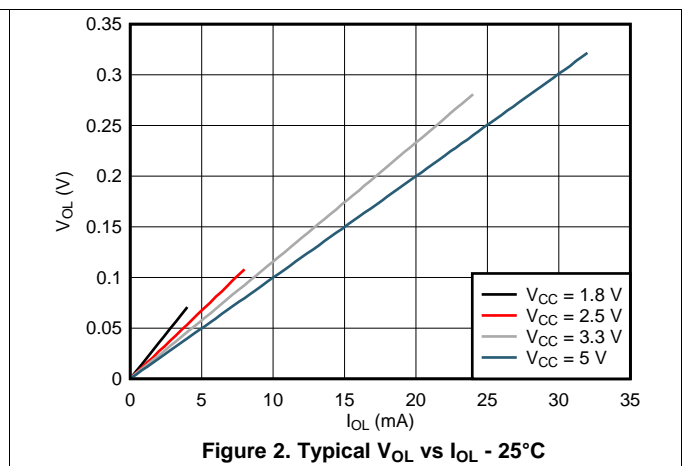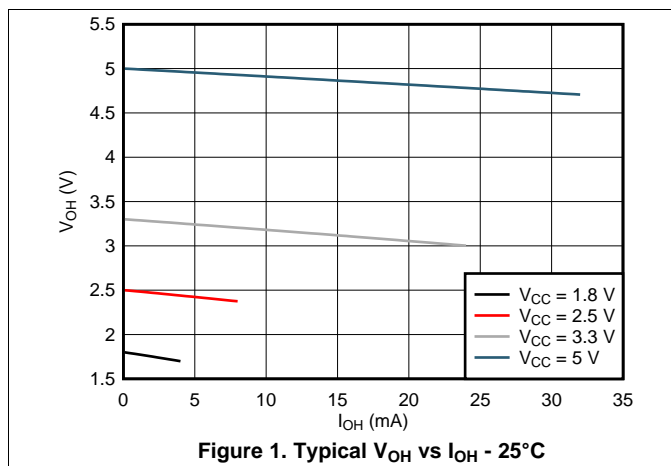
7 Parameter Measurement Information

- Input pulse is supplied by generator having the following characteristics: PRR ≤ 10MHz. $Z_O = 50\Omega$.
- The outputs are measured one at a time, with one transition per measurement.
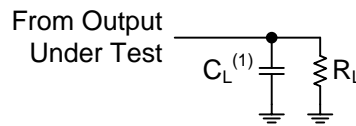
(1) C_L includes probe and jig capacitance.

Figure 3. Load Circuit

Table 1. Parameter Measurement Conditions

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_D
	V_I	t_r/t_f					
1.8 V ± 0.15 V	V_{cc}	≤ 2 ns	$V_{cc}/2$	2 × V_{cc}	15 pF	1 MΩ	0.15 V
					30 pF	1 kΩ	
2.5 V ± 0.2 V	V_{cc}	≤ 2 ns	$V_{cc}/2$	2 × V_{cc}	15 pF	1 MΩ	0.15 V
					30 pF	500 Ω	
3.3 V ± 0.3 V	3 V	≤ 2.5 ns	1.5 V	6 V	15 pF	1 MΩ	0.3 V
					50 pF	500 Ω	
5 V ± 0.5 V	V_{cc}	≤ 2.5 ns	$V_{cc}/2$	2 × V_{cc}	15 pF	1 MΩ	0.3 V
					50 pF	500 Ω	
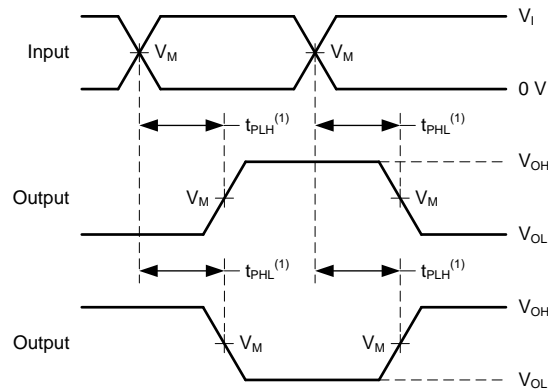
(1) The maximum value of t_{pd} is the worst case of t_{PLH} or t_{PHL}

Figure 4. Voltage Waveforms, Propagation Delay Times, Inverting and Non-Inverting Outputs

8 Detailed Description

8.1 Overview

The SN74LVC1G14 single Schmitt-trigger inverter is designed for 1.65 V to 5.5 V operation and performs the Boolean function Y = $\overline{A}$. This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs when the device is powered down. This inhibits current backflow into the device which prevents damage to the device.

8.2 Functional Block Diagrams
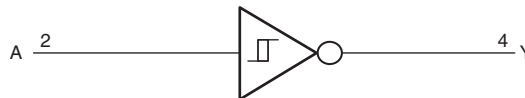
Figure 5. Logic Diagram (Positive Logic)
(DBV, DCK, DRL, DRY, DPW, and YZP Package)
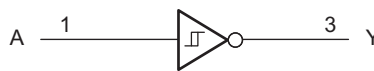
Figure 6. Logic Diagram (Positive Logic)
(YZV Package)

8.3 Feature Description

8.3.1 Balanced High-Drive CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The high drive capability of this device creates fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the power output of the device to be limited to avoid thermal runaway and damage due to over-current. The electrical and thermal limits defined the in the *Absolute Maximum Ratings*

Absolute Maximum Ratings] must be followed at all times.

8.3.2 CMOS Schmitt-Trigger Inputs

Standard CMOS inputs are high impedance and are typically modeled as a resistor in parallel with the input capacitance given in the *Electrical Characteristics*. The worst case resistance is calculated with the maximum input voltage, given in the *Absolute Maximum Ratings*, and the maximum input leakage current, given in the *Electrical Characteristics*, using ohm's law (R = V ÷ I).

The Schmitt-trigger input architecture provides hysteresis as define in the *Electrical Characteristics*, which makes this device extremely tolerant to slow or noisy inputs. While the inputs can be driven much slower than standard CMOS inputs, it is still recommended to properly terminate unused inputs. Driving the inputs slowly will also increase dynamic current consumption of the device.

Feature Description (continued)

8.3.3 Clamp Diodes

The inputs and outputs to this device have negative clamping diodes.

CAUTION

Voltages beyond the values specified in the *Absolute Maximum Ratings* table can cause damage to the device. The input negative-voltage and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
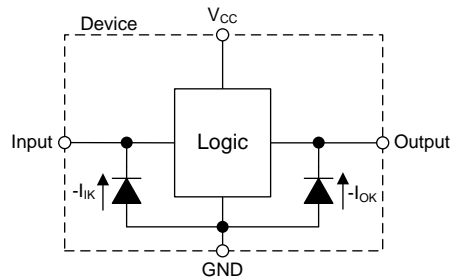
Figure 7. Electrical Placement of Clamping Diodes for Each Input and Output

8.3.4 Partial Power Down (I$_{off}$)

The inputs and outputs for this device enter a high impedance state when the supply voltage is 0 V. The maximum leakage into or out of any input or output pin on the device is specified by I$_{off}$ in the *Electrical Characteristics*.

8.3.5 Over-Voltage Tolerant Inputs

Input signals to this device can be driven above the supply voltage so long as they remain below the maximum input voltage value specified in the *Absolute Maximum Ratings*.

8.4 Device Functional Modes

Table 2 lists the functional modes of the SN74LVC1G14 device.

Table 2. Function Table

INPUT A	OUTPUT Y
H	L
L	H

Product Folder Links: *SN74LVC1G14*

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

Mechanical input elements, such as push buttons or rotary knobs, offer simple ways to interact with electronic systems. Typically, these elements have recoil or bouncing, where the mechanical element makes and breaks contact multiple times during human interaction. This bouncing can cause one or more repeated signals to be passed, triggering multiple actions when only a single input was intended. One potential solution to mitigating these multiple inputs is by utilizing a Schmitt-trigger to create a debounce circuit. Figure 8 shows an example of this solution.

9.2 Typical Application

The input due to the push button switches multiple times, causing the output of a non Schmitt-trigger device to trigger multiple times, while the Schmitt-trigger input device with RC delay limits the output pulse to a single pulse desired by the user. The separated positive and negative input voltage threshold values, see Figure 9, prevent multiple triggers from occurring.
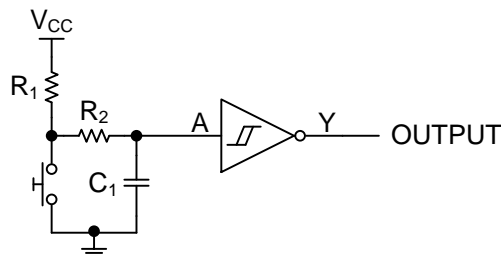
Figure 8. Push Button Debounce Circuit Schematic

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive also creates fast edges into light loads so routing and load conditions should be considered to prevent ringing.

9.2.2 Detailed Design Procedure

1. Recommended Input Conditions:
   – For specified high and low levels, see (V_{T+} and V_{T-}) in the *Recommended Operating Conditions* table.
   – Inputs are overvoltage tolerant allowing them to go as high as (V_I max) in the *Recommended Operating Conditions* table at any valid V_{CC}.
2. Recommended Output Conditions:
   – Load currents should not exceed (I_O max) per output and should not exceed (Continuous current through V_{CC} or GND) total current for the part. These limits are located in the *Absolute Maximum Ratings* table.

Typical Application (continued)

9.2.3 Application Curve

Figure 9 is created from the values given in the *Electrical Characteristics*. Linear interpolation shows the values between each given point.
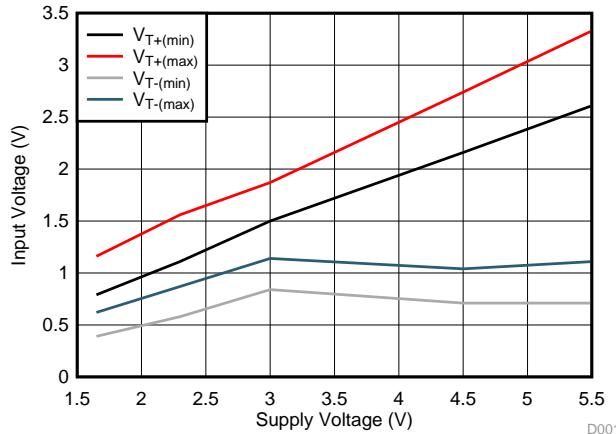

Figure 9. Interpolated Threshold Voltages vs. V_{CC}

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions* table.

The V_{CC} pin must have a good bypass capacitor to prevent power disturbance. A 0.1-µF capacitor is recommended, and it is ok to parallel multiple bypass caps to reject different frequencies of noise. 0.1-µF and 1-µF capacitors are commonly used in parallel. The bypass capacitor must be installed as close to the power pin as possible for best results.
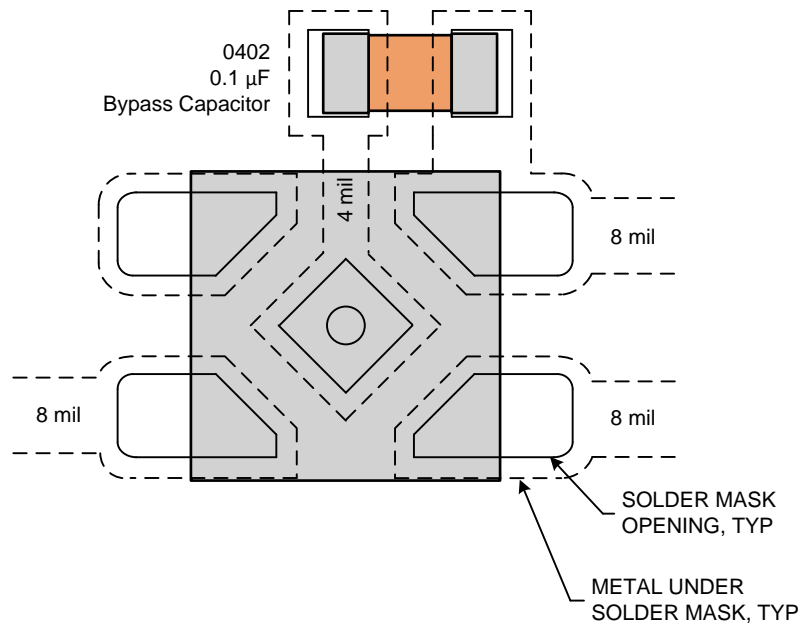
11 Layout

11.1 Layout Guidelines

Even low data rate digital signals can contain high-frequency signal components due to fast edge rates. When a printed-circuit board (PCB) trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self–inductance of the trace which results in the reflection. Not all PCB traces can be straight and therefore some traces must turn corners. shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

An example layout is given in Figure 10 for the DPW (X2SON-5) package. This example layout includes a 0402 (metric) capacitor and uses the measurements found in the example board layout appended to this end of this datasheet. A via of diameter 0.1 mm (3.973 mil) is placed directly in the center of the device. This via can be used to trace out the center pin connection through another board layer, or it can be left out of the layout

11.2 Layout Example

Figure 10. Example Layout With DPW (X2SON-5) Package

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

Implications of Slow or Floating CMOS Inputs

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

NanoFree, E2E are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.

12.5 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G14DBVR	SOT-23	DBV	5	3000	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74LVC1G14DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74LVC1G14DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G14DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G14DBVT	SOT-23	DBV	5	250	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74LVC1G14DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74LVC1G14DBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G14DCKR	SC70	DCK	5	3000	180.0	8.4	2.3	2.5	1.2	4.0	8.0	Q3
SN74LVC1G14DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G14DCKT	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G14DCKTG4	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G14DPWR	X2SON	DPW	5	3000	178.0	8.4	0.91	0.91	0.5	2.0	8.0	Q3
SN74LVC1G14DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
SN74LVC1G14DRYR	SON	DRY	6	5000	180.0	8.4	1.2	1.65	0.69	4.0	8.0	Q1
SN74LVC1G14DSFR	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q2
SN74LVC1G14YZPR	DSBGA	YZP	5	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

PACKAGE MATERIALS INFORMATION

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G14YZVR	DSBGA	YZV	4	3000	178.0	9.2	1.0	1.0	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G14DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G14DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G14DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74LVC1G14DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G14DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G14DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G14DBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G14DCKR	SC70	DCK	5	3000	210.0	185.0	35.0
SN74LVC1G14DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G14DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G14DCKTG4	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G14DPWR	X2SON	DPW	5	3000	205.0	200.0	33.0
SN74LVC1G14DRLR	SOT-5X3	DRL	5	4000	202.0	201.0	28.0
SN74LVC1G14DRYR	SON	DRY	6	5000	200.0	183.0	25.0
SN74LVC1G14DSFR	SON	DSF	6	5000	184.0	184.0	19.0
SN74LVC1G14YZPR	DSBGA	YZP	5	3000	220.0	220.0	35.0
SN74LVC1G14YZVR	DSBGA	YZV	4	3000	220.0	220.0	35.0

Images above are just a representation of the package family, actual package may vary.
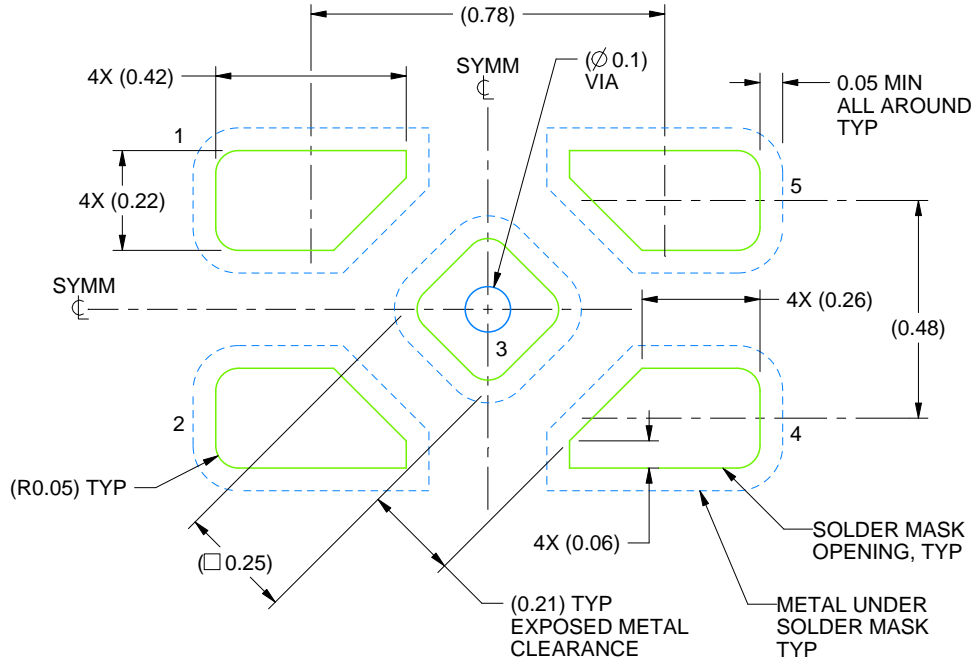Refer to the product data sheet for package details.

4211218-3/D

TEXAS
INSTRUMENTS

B — 0.85 / 0.75 — A

PIN 1 INDEX AREA

0.85 / 0.75

0.4 MAX

C

SEATING PLANE

NOTE 3

4X (0.05)

(0.324)

□ 0.25±0.1

(0.1)

0.05 / 0.00

NOTE 3

2

4

2X 0.48

3

2X (0.26)

1

5

0.239 / 0.139

4X 0.27 / 0.17

⊕	0.1 Ⓜ	C	A	B
	0.05 Ⓜ	C		

3X 0.288 / 0.188
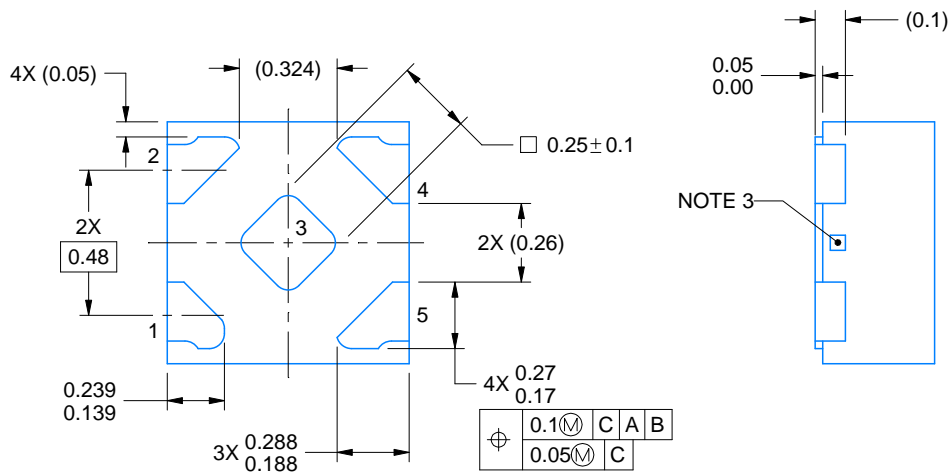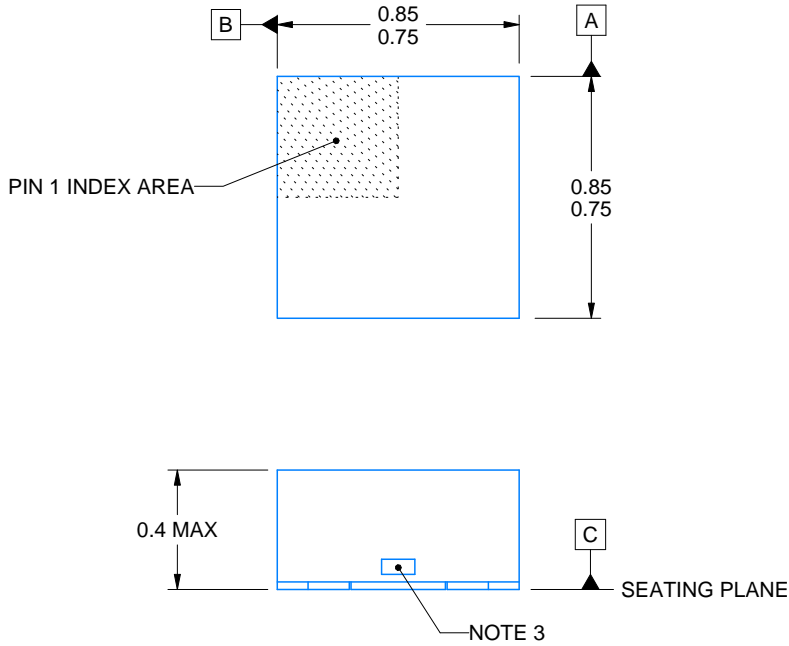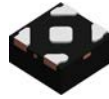
4223102/D   03/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The size and shape of this feature may vary.

(0.78)

4X (0.42)

SYMM

($\emptyset$ 0.1)
VIA

0.05 MIN
ALL AROUND
TYP

1

4X (0.22)

5

SYMM

3

4X (0.26)

(0.48)

2

4

(R0.05) TYP

4X (0.06)

SOLDER MASK
OPENING, TYP

($\square$ 0.25)

(0.21) TYP
EXPOSED METAL
CLEARANCE

METAL UNDER
SOLDER MASK
TYP

LAND PATTERN EXAMPLE
SOLDER MASK DEFINED
SCALE:60X

4223102/D   03/2022

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note
   in literature No. SLUA271 (www.ti.com/lit/slua271).

4X (0.42)

4X (0.06)

4X (0.22)

1

4X (0.26)

5

(□ 0.24)

SYMM

SOLDER MASK
EDGE

(0.21)
TYP

(0.48)

3

2

4

(R0.05) TYP

SYMM

(0.78)
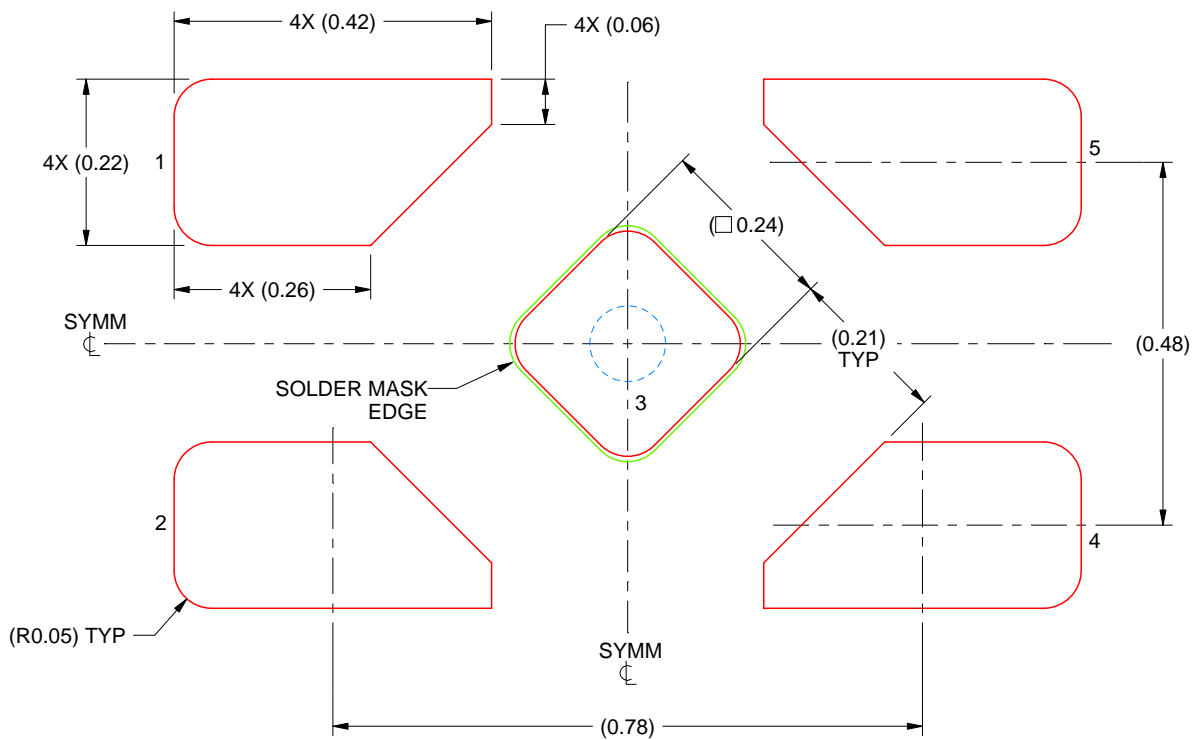
SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 3
92% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:100X

4223102/D   03/2022
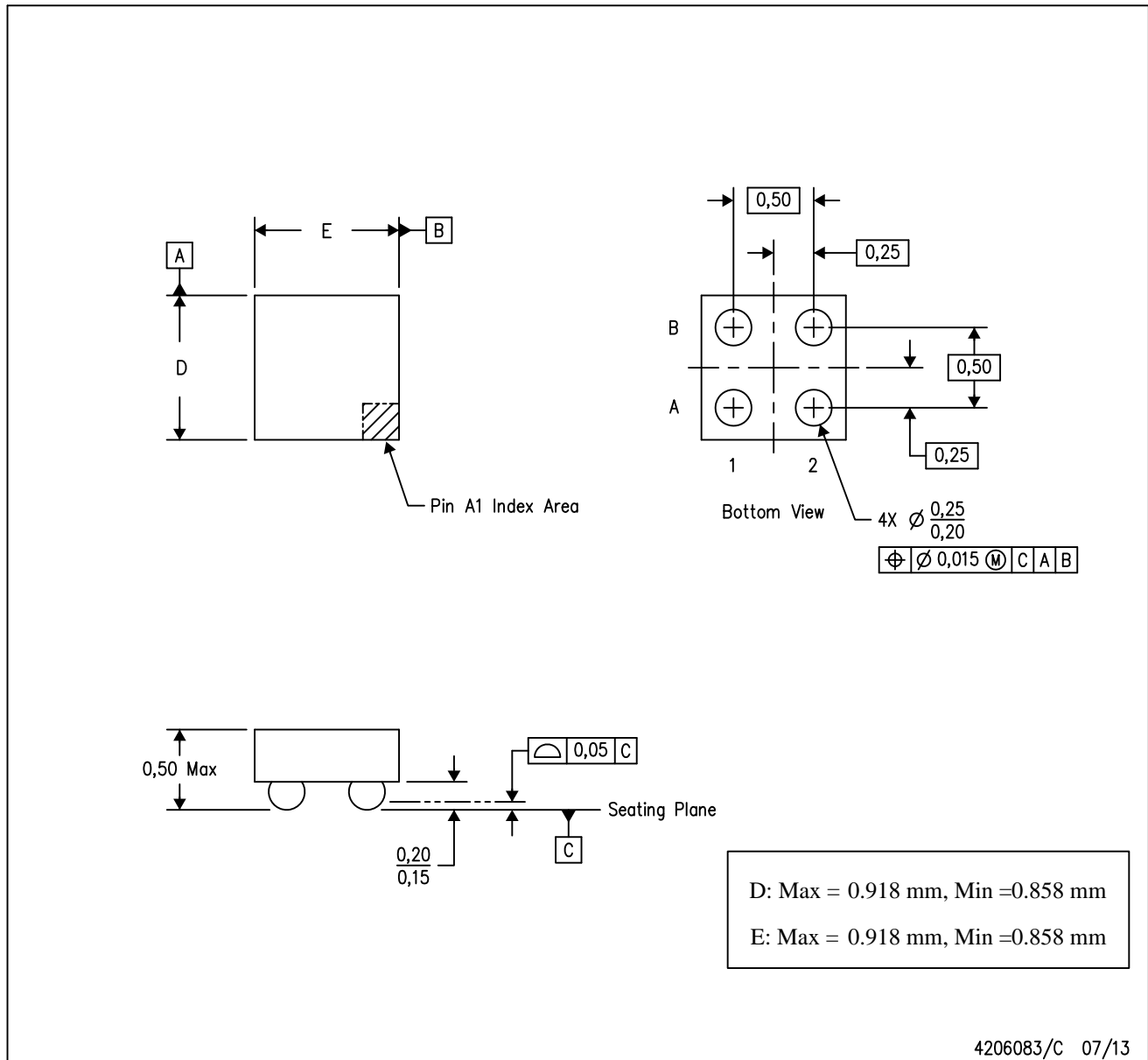
NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
design recommendations.

B ◄— E —► A

BALL A1
CORNER

D

0.5 MAX

0.19
0.15

BALL TYP

C

SEATING PLANE

⌓ 0.05 C

0.5 TYP

C

B

SYMM
₵

1
TYP

0.5
TYP

A

5X ⌀ 0.25
0.21

⊕ 0.015Ⓜ C A B

1   2

SYMM
₵

D: Max = 1.418 mm, Min =1.358 mm

E: Max = 0.918 mm, Min =0.858 mm

4219492/A   05/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing
   per ASME Y14.5M.
2. This drawing is subject to change without notice.

5X (∅ 0.23)

(0.5) TYP

(0.5) TYP

1   2

A

B

C

SYMM
₵

SYMM
₵
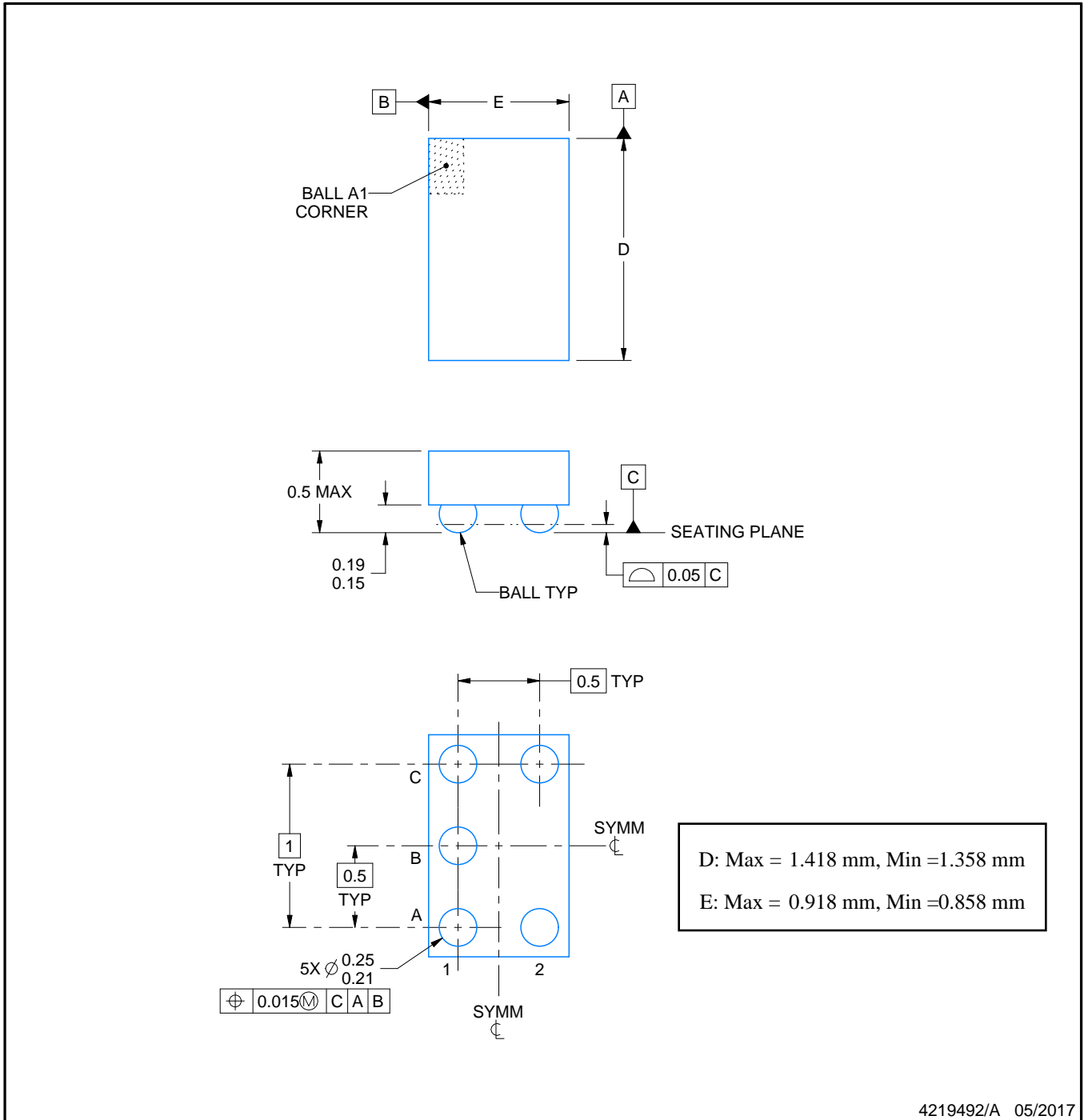
LAND PATTERN EXAMPLE
SCALE:40X

SOLDER MASK
OPENING

0.05 MAX

(∅ 0.23)
METAL

**NON-SOLDER MASK
DEFINED
(PREFERRED)**

0.05 MIN

(∅ 0.23)
SOLDER MASK
OPENING

METAL UNDER
SOLDER MASK

**SOLDER MASK
DEFINED**

SOLDER MASK DETAILS
NOT TO SCALE

4219492/A   05/2017

NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
   For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

(0.5) TYP

5X (☐ 0.25)

(R0.05) TYP
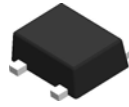
1

2

A

(0.5) TYP

B

SYMM
℄

C

METAL TYP

SYMM
℄

SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4219492/A   05/2017

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

YZV (S−XBGA−N4)   DIE−SIZE BALL GRID ARRAY

Pin A1 Index Area

Bottom View

4X Ø 0,25 / 0,20

⊕ Ø 0,015 Ⓜ C A B

0,50 Max

0,20 / 0,15

Seating Plane

0,05 C

D: Max = 0.918 mm, Min =0.858 mm

E: Max = 0.918 mm, Min =0.858 mm

4206083/C   07/13

NOTES: A.   All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
          B.   This drawing is subject to change without notice.
          C.   NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments.

Texas Instruments
www.ti.com

PIN 1
INDEX AREA

3.0
2.6

1.75
1.45

B

A

1

5

2X 0.95

1.9

2

3.05
2.75

1.9

(0.1)

(0.15)

3

4

5X 0.5
0.3

⊕ 0.2Ⓜ C A B

NOTE 5

C

⌒ 0.1 C

1.45
0.90

(1.1)

0.15 TYP
0.00

0.25

GAGE PLANE

0.22 TYP
0.08

8° TYP
0°

0.6 TYP
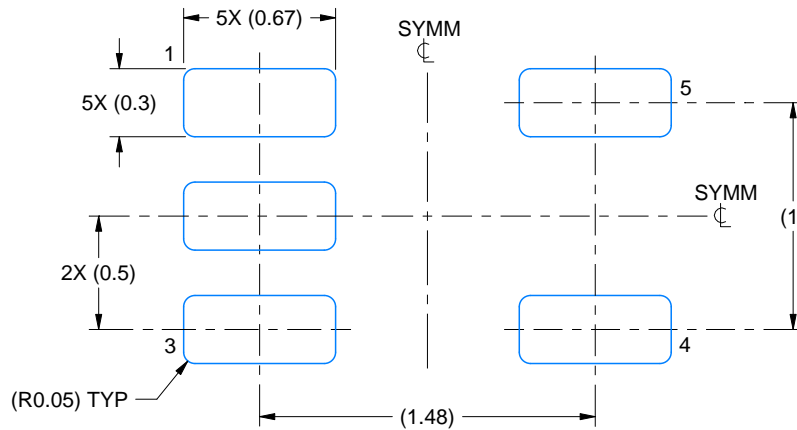0.3

SEATING PLANE
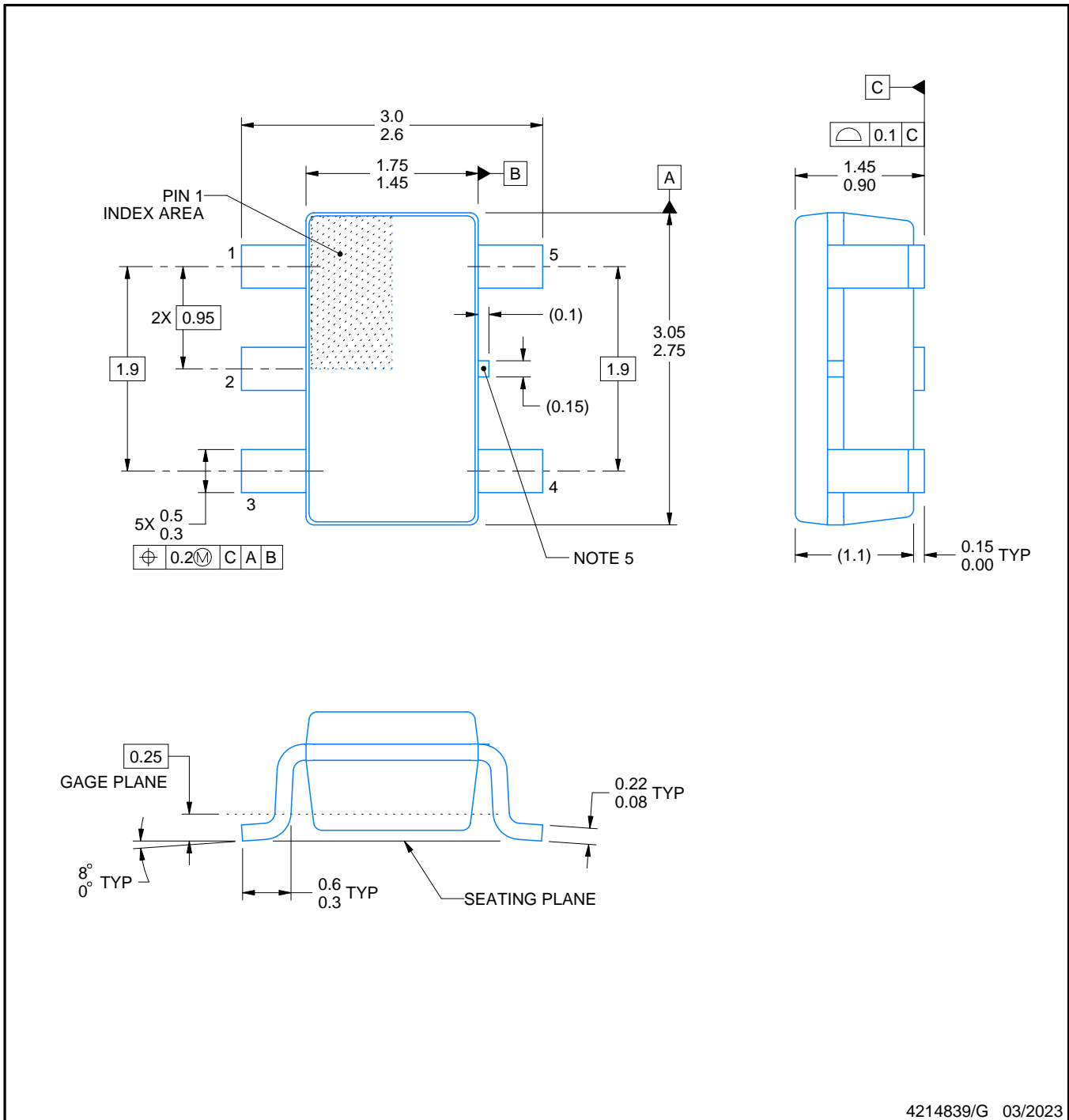
4214839/G   03/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

PKG ℄

5X (1.1)

1

5X (0.6)

5

SYMM ℄

2

(1.9)

2X (0.95)

3

4

(R0.05) TYP

(2.6)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.07 MAX
ARROUND

NON SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.07 MIN
ARROUND

SOLDER MASK
DEFINED
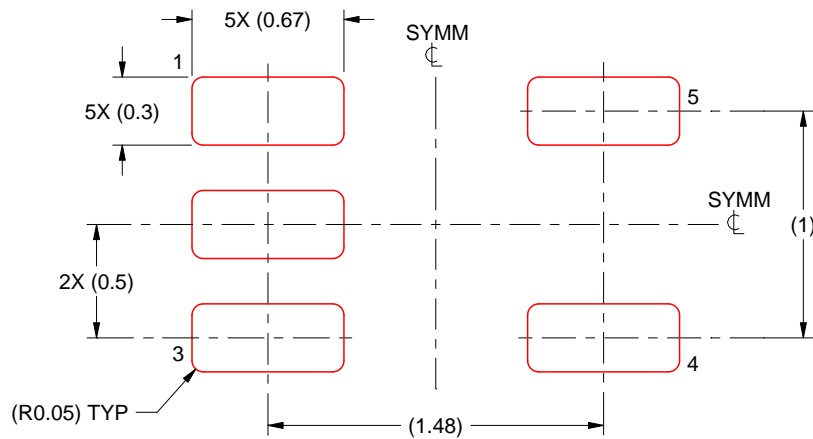
SOLDER MASK DETAILS

4214839/G   03/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

PKG

5X (1.1)

1

5X (0.6)

5

SYMM

2

(1.9)

2X(0.95)

3

4

(R0.05) TYP

(2.6)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214839/G   03/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DRL0005A

PLASTIC SMALL OUTLINE

1.7
1.5

PIN 1
ID AREA

A

1
2X 0.5
2X 1
3

5

1.7
1.5
NOTE 3

4

B
1.3
1.1

5X 0.3
0.1

0.05 TYP
0.00

0.6 MAX

C

SEATING PLANE

5X 0.18
0.08

0.05 C

SYMM
℄

SYMM
℄

5X 0.27
0.15

5X 0.4
0.2

⊕ 0.1 Ⓜ C A B
0.05 Ⓜ
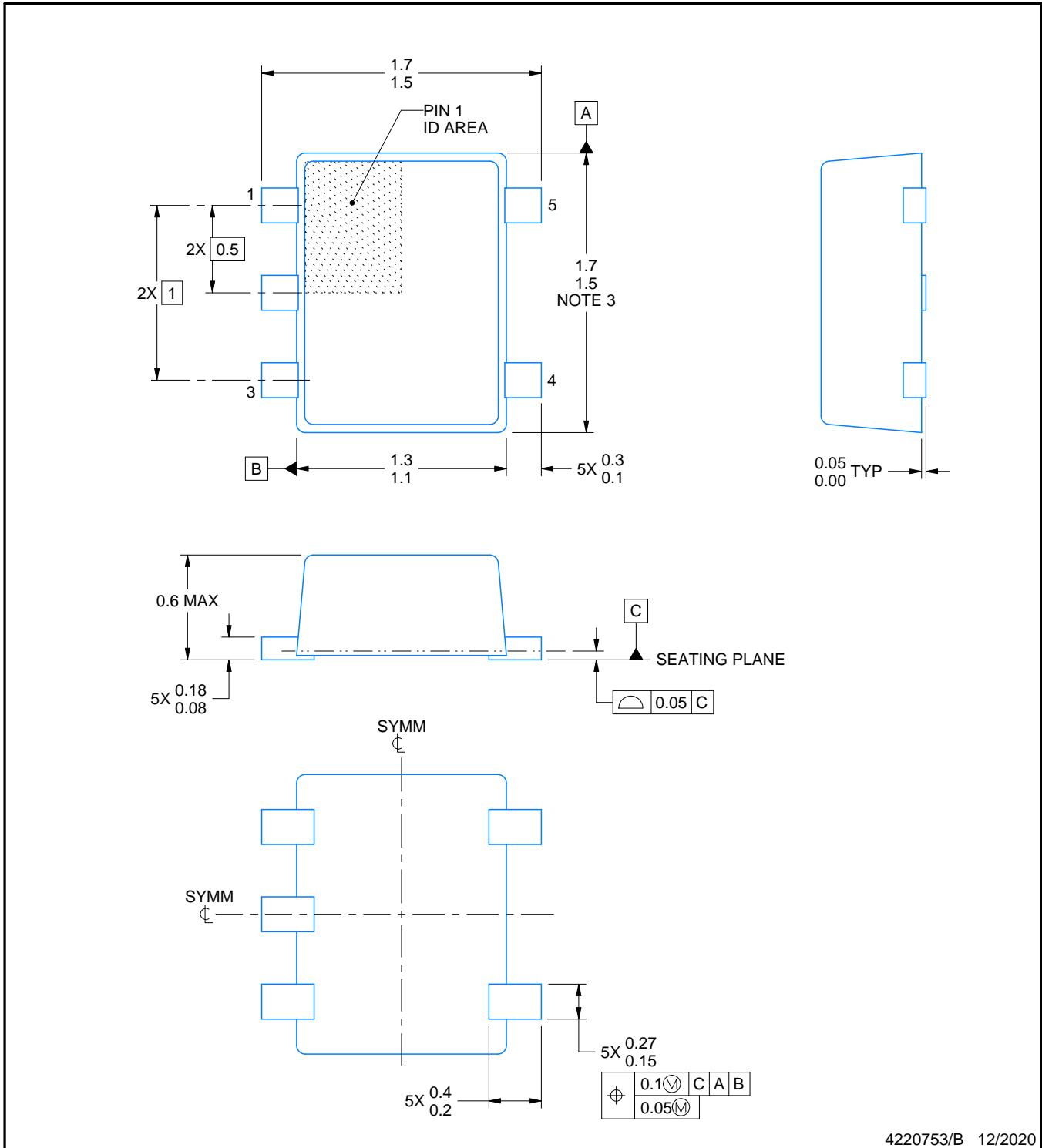
4220753/B   12/2020

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

5X (0.67)

SYMM
℄

1

5X (0.3)

5

SYMM
℄

(1)

2X (0.5)

3

4

(R0.05) TYP

(1.48)

LAND PATTERN EXAMPLE
SCALE:30X

0.05 MAX
AROUND

SOLDER MASK
OPENING

METAL

**NON SOLDER MASK
DEFINED
(PREFERRED)**

0.05 MIN
AROUND

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

**SOLDER MASK
DEFINED**
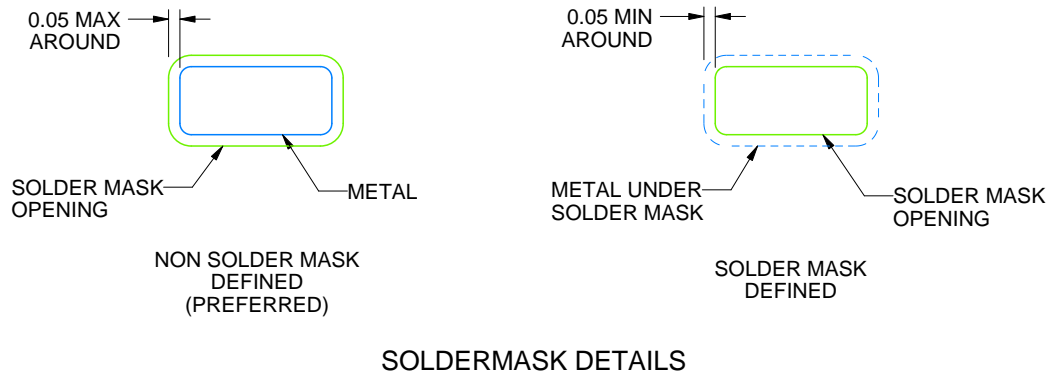
SOLDERMASK DETAILS

4220753/B 12/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

5X (0.67)

SYMM

1

5X (0.3)

5

SYMM

(1)

2X (0.5)

3

4

(R0.05) TYP

(1.48)

SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4220753/B   12/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
    design recommendations.
8. Board assembly site may have different recommendations for stencil design.
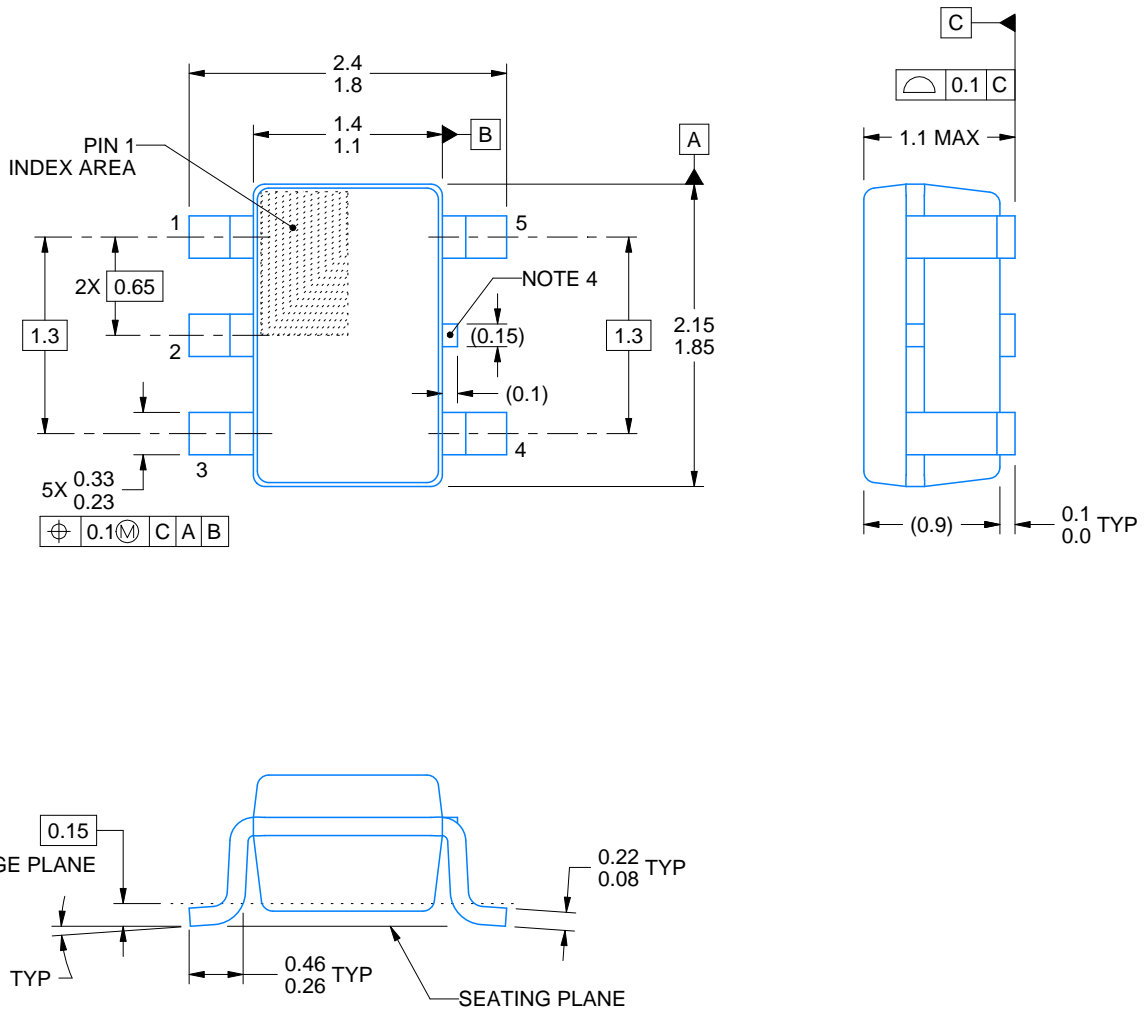
4214834/C   03/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-203.
4. Support pin may differ or may not be present.

5X (0.95)

PKG ℄

1

5X (0.4)

5

SYMM ℄

2

(1.3)

2X (0.65)

3

4

(R0.05) TYP

(2.2)
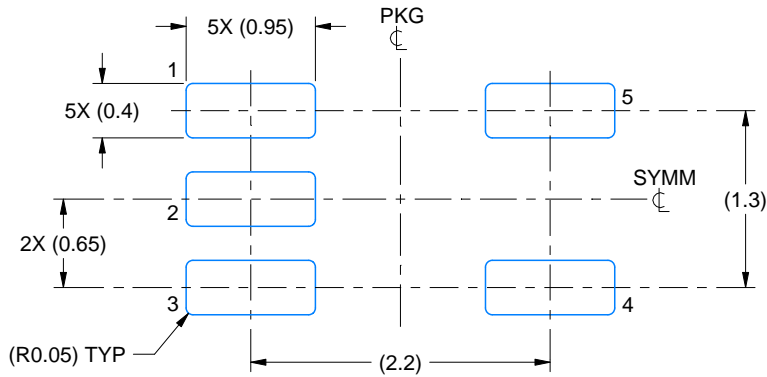
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.07 MAX
ARROUND

NON SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.07 MIN
ARROUND

SOLDER MASK
DEFINED
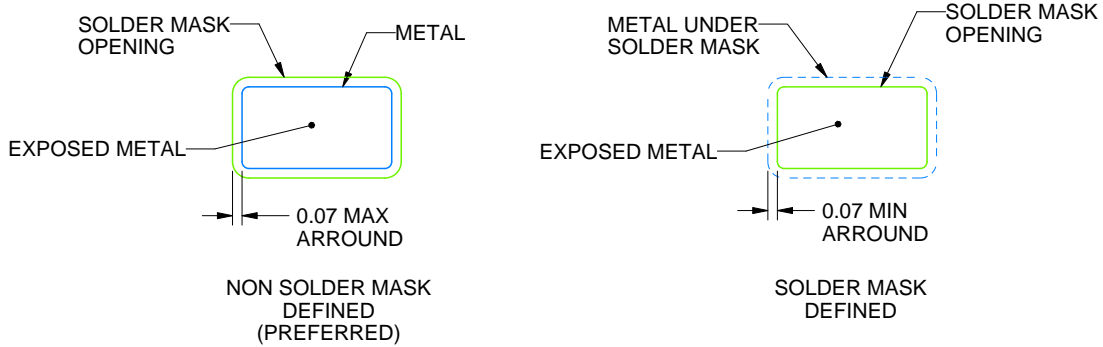
SOLDER MASK DETAILS

4214834/C   03/2023

NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

TEXAS
INSTRUMENTS
www.ti.com

PKG
℄

5X (0.95)

1

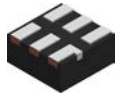5X (0.4)

2

5

SYMM
℄

(1.3)

2X(0.65)

3

4

(R0.05) TYP

(2.2)

SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/C   03/2023

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
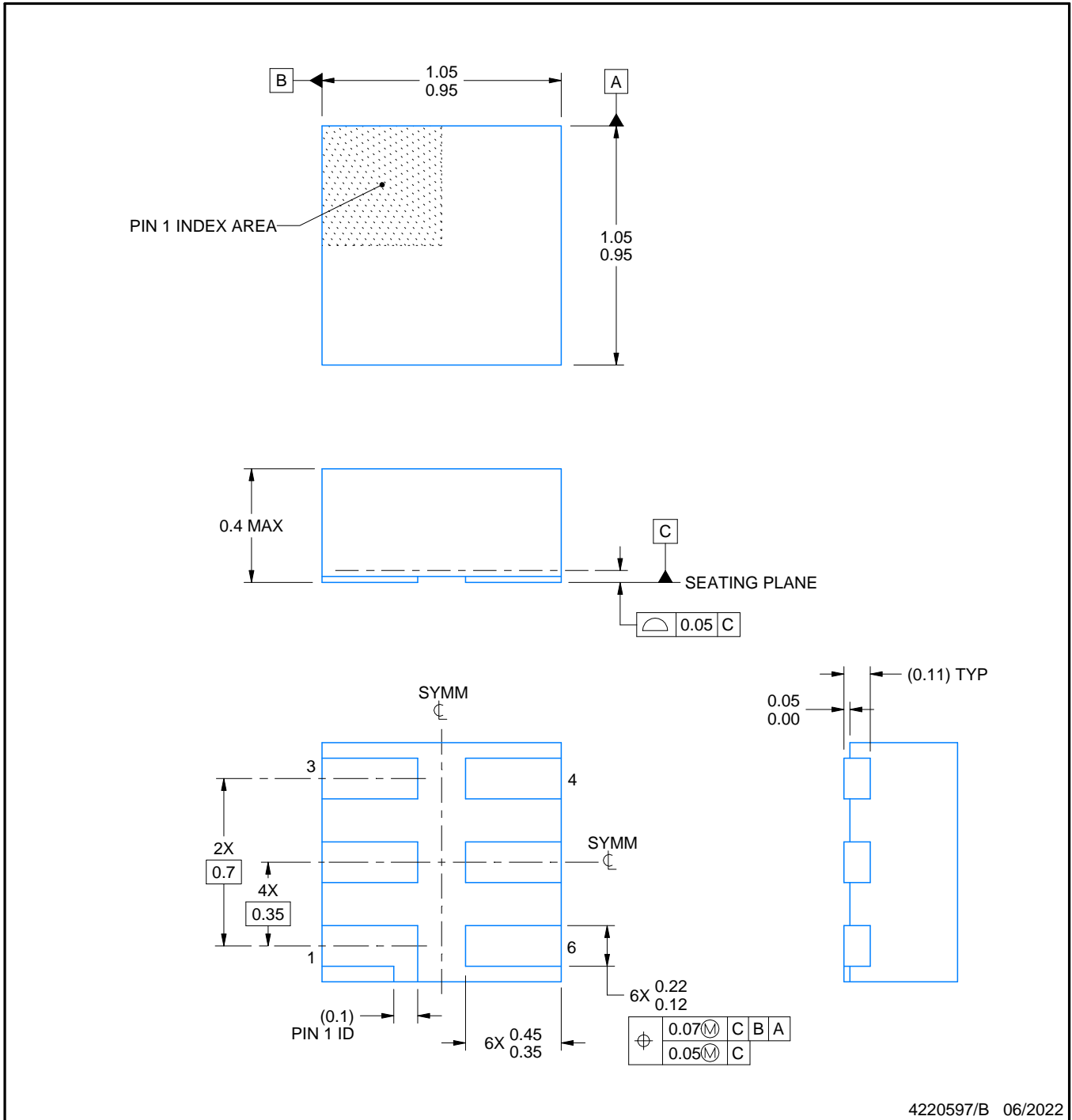7. Board assembly site may have different recommendations for stencil design.

Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4207181/G

B | 1.05 / 0.95 | A

PIN 1 INDEX AREA

1.5 / 1.4

0.6 MAX

C

0.05 / 0.00

SEATING PLANE

0.08 | C

3X | 0.6

SYMM

(0.05) TYP

3

4

4X
0.5

SYMM

2X
1

1

6

0.4
0.3

6X 0.25 / 0.15

⊕ | 0.1Ⓜ | C | A | B
| 0.05Ⓜ | C

PIN 1 ID
(OPTIONAL)

5X 0.35 / 0.25

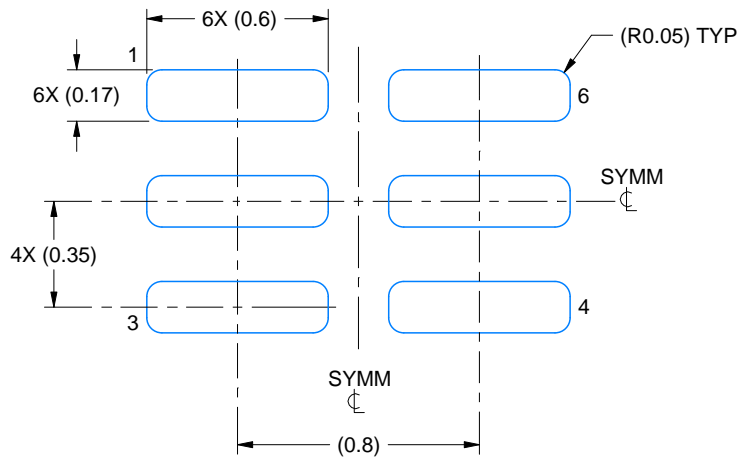(0.127) TYP

4222894/A   01/2018

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

SYMM
(0.35)
5X (0.3)

1

6

6X (0.2)

SYMM

4X (0.5)

3

4

(R0.05) TYP

(0.6)
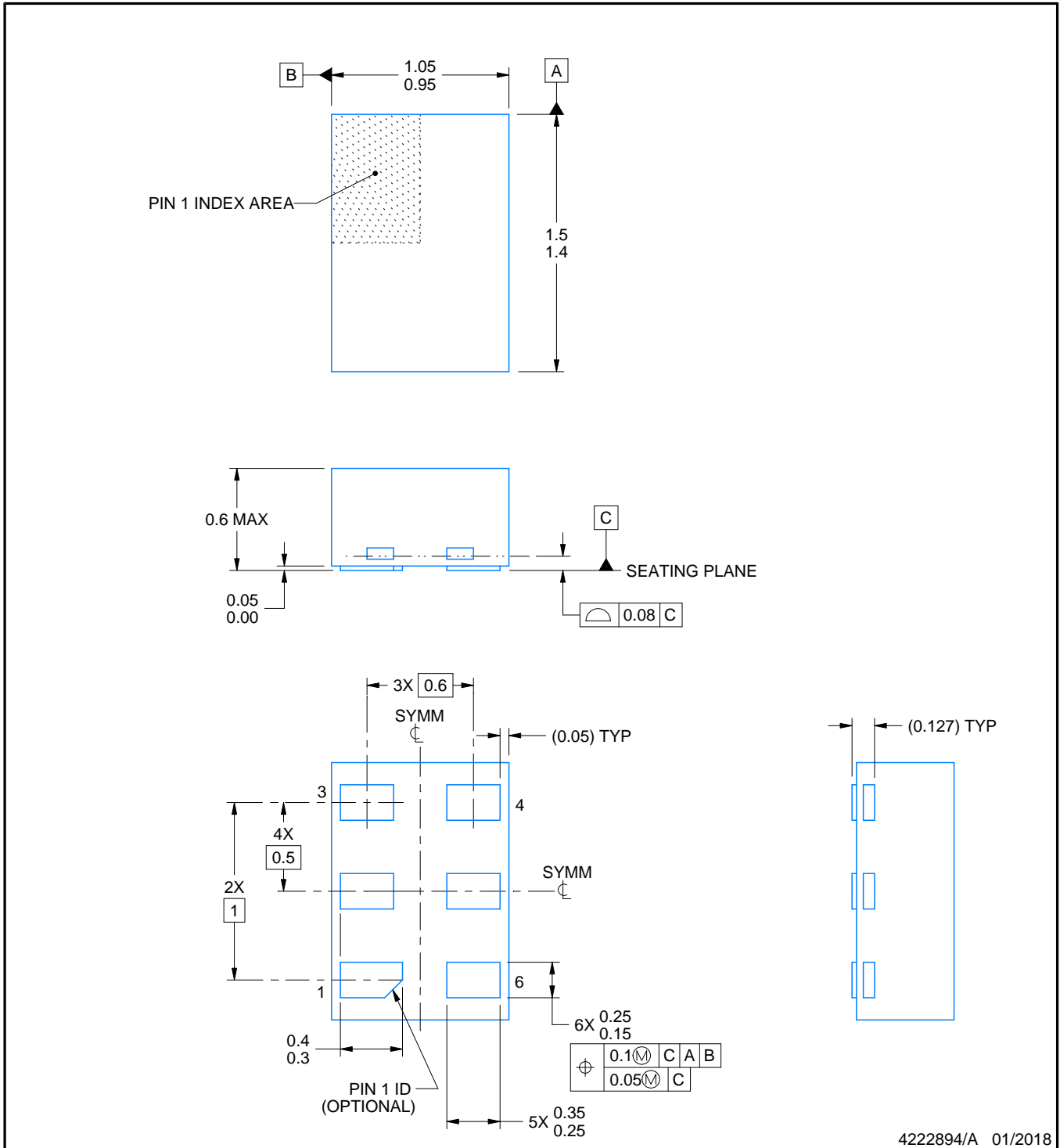
LAND PATTERN EXAMPLE
1:1 RATIO WITH PKG SOLDER PADS
EXPOSED METAL SHOWN
SCALE:40X

0.05 MAX
ALL AROUND

EXPOSED
METAL

SOLDER MASK
OPENING

METAL

NON SOLDER MASK
DEFINED

0.05 MIN
ALL AROUND

EXPOSED
METAL

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK DETAILS

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NOTES: (continued)

3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).

SYMM

(0.35)

5X (0.3)

1

6

6X (0.2)

SYMM

4X (0.5)

3

4

(R0.05) TYP

(0.6)

SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1 mm THICK STENCIL
SCALE:40X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.

1.05
0.95

B

A

1.05
0.95

PIN 1 INDEX AREA

0.4 MAX

C

SEATING PLANE

⌓ 0.05 C

(0.11) TYP

0.05
0.00

SYMM

3

4

2X
0.7

SYMM

4X
0.35

1

6

(0.1)
PIN 1 ID

6X 0.45
0.35

6X 0.22
0.12

⊕ 0.07 Ⓜ C B A
0.05 Ⓜ C

4220597/B 06/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

6X (0.6)

1

6X (0.17)

(R0.05) TYP

6

SYMM
℄

4X (0.35)

3

4

SYMM
℄

(0.8)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:40X

0.07 MAX
ALL AROUND

EXPOSED METAL

SOLDER MASK
OPENING

METAL

NON SOLDER MASK
DEFINED

0.07 MIN
ALL AROUND

EXPOSED METAL

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

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NOTES: (continued)

4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

6X (0.6)

1

6X (0.15)

6

(R0.05) TYP

SYMM

4X (0.35)

3

4

SYMM

(0.8)

SOLDER PASTE EXAMPLE
BASED ON 0.09 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:40X

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4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.

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